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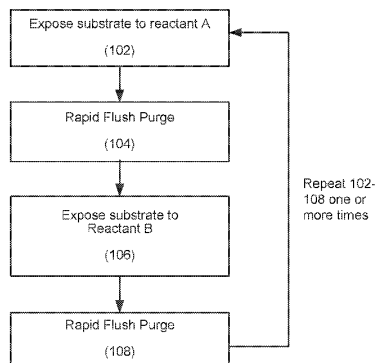
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(54) Title: RAPID FLUSH PURGING DURING ATOMIC LAYER DEPOSITION



(57) Abstract: Provided herein are methods and related apparatus for purging processing chambers during an atomic layer deposition (ALD) process. The methods involve flowing purging gas from one or more accumulators to remove process gases from the processing chambers. Following the flowing of purging gas, additional reactants may be introduced into the processing chamber to continue an ALD cycle.

FIG. 1

[Continued on next page]

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